

## Epi Fine EX-0064

Epi Fine EX-0064 a one-component epoxy adhesive is designed specifically for low temperature hardening. And EX-0064 is same EP-171. But this resin is low gas type.

### 1 . General Characters

Appearance	Viscosity	Thixotropic Factor	Specific Gravity
Blown , thixotropic liquid	28,000 mPa· s.	1.7	1.3

### 2 . Storage and cure condition

Storage Life		Gel time	Recommended cure condition
5 degree C	25 degree C	80 degree C	80 degree C
5 Months	30 Days	25 minutes	60 minutes

### 3 . Cured property

Item	Typical Values	Test Method	
Hardness	87 Shore D	JIS-K-7215	
Modulus of elasticity	4,100 MPa	JIS-K-6911	
Bending strength	55 MPa	JIS-K-6911	
Glass transition temperature	84 Degree C	JIS-K-7197	
Thermal expansion	$6.2 \times 10^{-5}$	JIS-K-7197	
Bonding strength	13.0 MPa ( Fe /Fe )	at 25°C	JIS-K-6850
Water absorption	0.9 Weight %	JIS-K-6911	

The figures shown above are typical values only.



**FINE POLYMERS CORPORATION** RESEARCH & DEVELOPMENT DEPT.

Address : 353,NISHIGOUYA, NODA-CITY CHIBA PREF. JAPAN

TEL : +81-4-7196-1144 FAX : +81-4-7196-1141

Home Page : <http://www.fine-polymers.co.jp>